

### W15NK90Z-VB Datasheet

## **Super Junction Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	900			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.27		
Q <sub>g</sub> max. (nC)	122			
Q <sub>gs</sub> (nC)	14			
Q <sub>gd</sub> (nC)	23			
Configuration	Single			

#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qa)
- Avalanche energy rated (UIS)



#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
- Renewable energy
- Solar (PV inverters)

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	N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			$V_{DS}$	900	V	
Gate-source voltage			$V_{GS}$	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I <sub>D</sub>	20	А	
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		10		
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	60		
Linear derating factor				1.7	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	383	mJ	
Maximum power dissipation			$P_{D}$	218	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope	T <sub>J</sub> = 125 °C		dV/dt	70	V/ns	
Reverse diode dV/dt <sup>d</sup>			av/at	5.1	V/IIS	
Soldering recommendations (peak temperature) <sup>c</sup>	For 10 s			300	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 5.0 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$



THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R <sub>thJA</sub>	=	62	°C/W		
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.6	G/ VV		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static		-				•	
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	900	_	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	1.08	-	V/°C
Gate-source threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		-	4.0	V
	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage			$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
		V <sub>DS</sub> =	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 640 \	V <sub>DS</sub> = 640 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		=	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 8.5 A	-	0.27	-	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 8.5 A		-	8.7	-	S
Dynamic		•					
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 100 V, f = 1 MHz		-	2408	-	pF
Output capacitance	C <sub>oss</sub>			-	81	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	9	-	
Effective output capacitance, energy related <sup>a</sup>	$C_{o(er)}$	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	58	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	296	-	
Total gate charge	Qg			-	61	122	
Gate-source charge	$Q_{gs}$	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 8.5 \text{ A}, V_{DS} = 480 \text{ V}$		14	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	23	-	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD} = 480 \text{ V}, I_{D} = 8.5 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	22	44	
Rise time	t <sub>r</sub>			-	24	48	
Turn-off delay time	t <sub>d(off)</sub>			-	71	142	ns
Fall time	t <sub>f</sub>			-	26	52	
Gate input resistance	$R_g$	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	
Pulsed diode forward current	I <sub>SM</sub>			-	-	45	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8.5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 8.5 A, dl/dt = 100 A/ $\mu$ s, V <sub>R</sub> = 25 V		-	416	832	ns
Reverse recovery charge	Q <sub>rr</sub>			-	6.4	12.8	μC
Reverse recovery current	I <sub>RRM</sub>			-	27	-	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$  b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$

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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

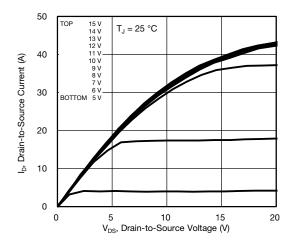


Fig. 1 - Typical Output Characteristics

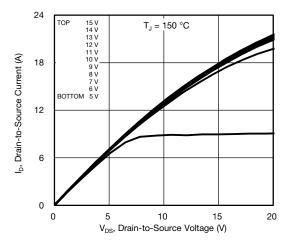


Fig. 2 - Typical Output Characteristics

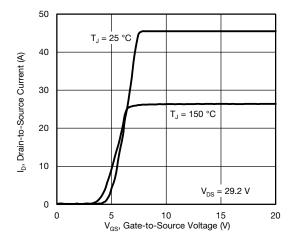


Fig. 3 - Typical Transfer Characteristics

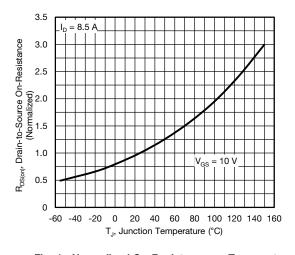


Fig. 4 - Normalized On-Resistance vs. Temperature

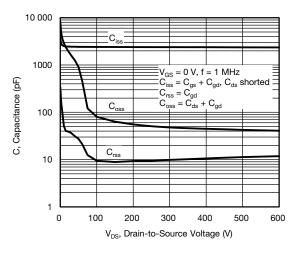


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

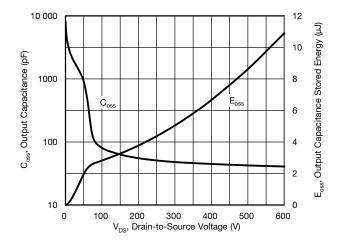


Fig. 6 - Coss and Eoss vs. VDS



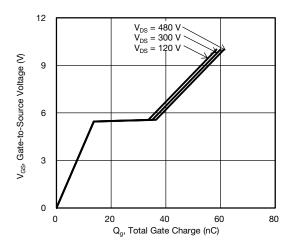


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

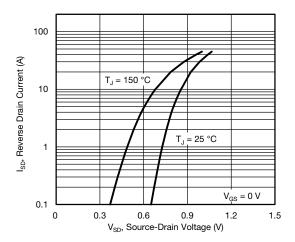


Fig. 8 - Typical Source-Drain Diode Forward Voltage

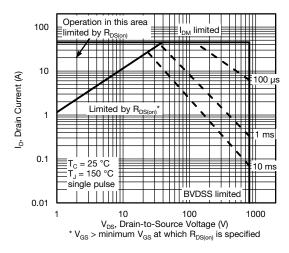


Fig. 9 - Maximum Safe Operating Area

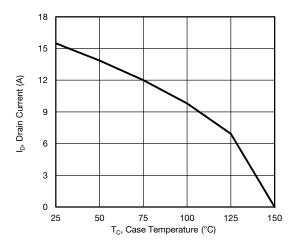


Fig. 10 - Maximum Drain Current vs. Case Temperature

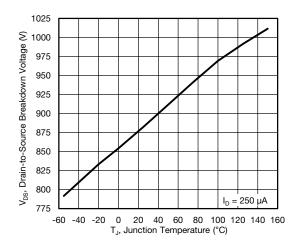


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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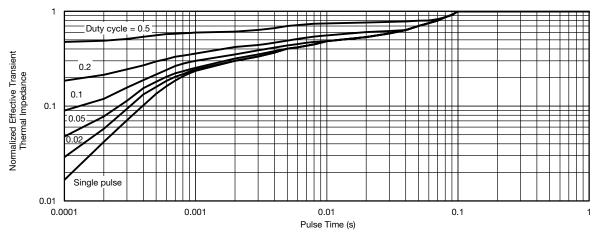


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

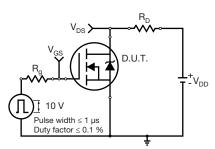


Fig. 13 - Switching Time Test Circuit

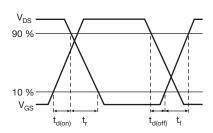


Fig. 14 - Switching Time Waveforms

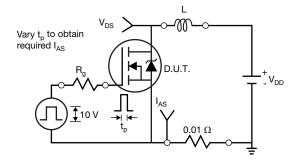


Fig. 15 - Unclamped Inductive Test Circuit

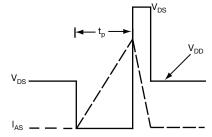


Fig. 16 - Unclamped Inductive Waveforms

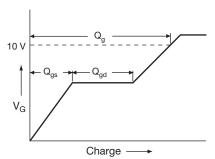


Fig. 17 - Basic Gate Charge Waveform

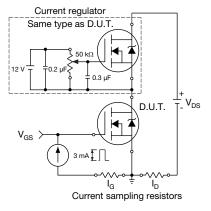
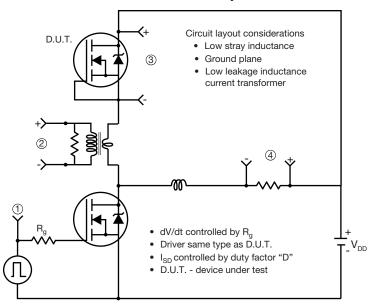


Fig. 18 - Gate Charge Test Circuit

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#### Peak Diode Recovery dV/dt Test Circuit



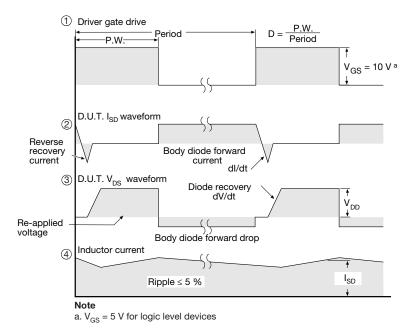


Fig. 19 - For N-Channel

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